TOSHIBA Power MOS FET Module Silicon N Channel MOS Type (L<sup>2</sup>-π-MOSV 4 in 1)

# **MP4410**

High Power, High Speed Switching Applications.

Hammer Drive, Pulse Motor Drive and Inductive Load Switching.

- 4 V gate drive available
- Small package by full molding (SIP 12 pin)
- High drain power dissipation (4 devices operation)

 $: P_T = 28 \text{ W (Tc} = 25^{\circ}\text{C)}$ 

- Low drain-source ON resistance: RDS (ON) =  $0.12 \Omega$  (typ.)
- Low leakage current:  $I_{GSS} = \pm 10 \mu A \text{ (max) (V}_{GS} = \pm 16 \text{ V)}$

 $I_{DSS} = 100 \,\mu A \,(max) \,(V_{DS} = 60 \,V)$ 

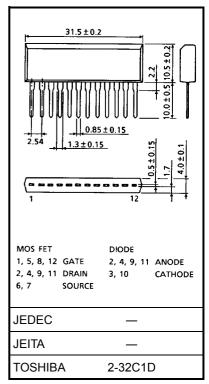
• Enhancement-mode:  $V_{th} = 0.8 \text{ to } 2.0 \text{ V (ID} = 1 \text{ mA)}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	60	V
Gate-source voltage		V <sub>GSS</sub>	±20	V
Drain current		I <sub>D</sub>	5	Α
Peak drain current		I <sub>DP</sub>	20	Α
Drain power dissipation (1 device operation)		P <sub>D</sub>	2.2	W
Drain power dissipation (4 devices operation)	Ta = 25°C	P <sub>T</sub>	4.4	W
	Tc = 25°C	FI	28	VV
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature range		T <sub>stg</sub>	−55 to 150	°C

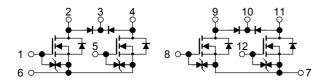
#### **Industrial Applications**

Unit: mm



Weight: 3.9 g (typ.)

#### **Array Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit	
Thermal resistance of channel to ambient	ΣR <sub>th (ch-a)</sub>	28.4	°C/W	
(4 devices operation, Ta = 25°C)	, ,			
Thermal resistance of channel to case		4.46	°C/W	
(4 devices operation, Tc = 25°C)	ΣR <sub>th (ch-c)</sub>	4.40	C/VV	
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for 10 s)	_			

This Transistor is an Electrostatic Sensitive Device. Please Handle with Caution.

### **Electrical Characteristics (Ta = 25°C)**

Chara	cteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curr	ent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brea	kdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	60	_	_	V
Gate threshold vo	Itage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	8.0	_	2.0	V
Forward transfer a	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.5 A	3.0	5.0	_	S
Drain-source ON resistance	Б	I <sub>D</sub> = 2.5 A, V <sub>GS</sub> = 4 V	_	0.21	0.31	Ω	
Dialii-source ON	resistance	R <sub>DS</sub> (ON)	I <sub>D</sub> = 2.5 A, V <sub>GS</sub> = 10 V	_	0.12	0.16	Ω
Input capacitance		C <sub>iss</sub>		_	370	_	pF
Reverse transfer of	capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	60	_	pF
Output capacitance		C <sub>oss</sub>		_	180	_	pF
Switching time  Turn-on time  Fall time  Turn-off time	Rise time	t <sub>r</sub>	$I_{D} = 2.5 \text{ A}$ $10 \text{ V}_{\text{IN}}$ $0 \text{ V}_{\text{IN}}$ $0 \text{ C}_{\text{CI}}$	_	18	_	
	Turn-on time	t <sub>on</sub>		_	25	1	ns
	t <sub>f</sub>	10 μs	_	15		113	
	Turn-off time	t <sub>off</sub>	V <sub>IN</sub> : t <sub>r</sub> , t <sub>f</sub> < 5 ns, dutys cycle ≤ 1%	_	170	_	
Total gate charge (gate-source plus gate-drain)		Qg	I <sub>D</sub> = 5 A, V <sub>GS</sub> = 10 V, V <sub>DD</sub> = 48 V	_	12	_	nC
Gate-source charge		Q <sub>gs</sub>		_	8	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>			4	_	nC

## **Source-Drain Diode Rating and Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	$I_{DR}$	_	_	_	5	Α
Peak drain reverse current	I <sub>DRP</sub>	_	_	_	20	Α
Diode forward voltage	V <sub>DSF</sub>	I <sub>DR</sub> = 5 A, V <sub>GS</sub> = 0 V	_		-1.7	V

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# Flyback-Diode Rating and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Maximum forward current	I <sub>FM</sub>	_	_	_	5	Α
Reverse current	I <sub>R</sub>	V <sub>R</sub> = 120 V	_	_	0.4	μΑ
Reverse voltage	V <sub>R</sub>	I <sub>R</sub> = 100 μA	120	_	_	V
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 1 A	_	_	1.8	V

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